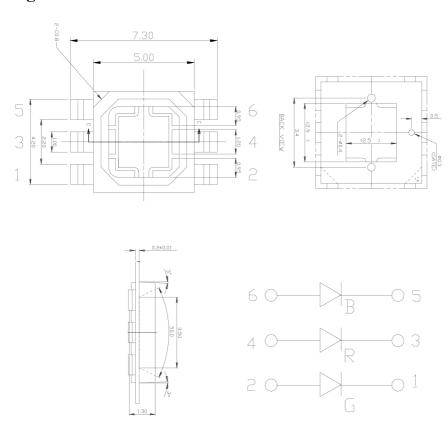


Features:

- ♦ High intensity
- ◆ Surface Mount Package
- ◆Red&Green&Blue 3in1
- ◆ Reliable and rugged

Package Dimensions:



Part No.	Chip Material	Lens Color	Source Color
TL-HPSRGB1-2	InGaN& AlGalnP	Water Clear	RGB

Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25 mm (.010")unless otherwise noted.
- 3. Protruded resin under flange is 1.0mm(.04")max.
- 4.Lead spacing is measured where the leads emerge from the package.
- 5. Specifications are subject to change without notice.
- 6.Precautions for **ESD**:

STATIC SHIELD Electricity and surge damages the **LED**. It is recommended to use a wrist band or anti-electrostatic glove when handling the **LED**. All devices, equipment and machinery must be properly grounded.

7. This data-sheet only valid for six months.



Absolute Maximum Ratings at Ta=25 ℃

Parameter	MAX.	Unit		
Power Dissipation	1200	mW		
Peak Forward Current (1/10 Duty Cycle,0.1ms Pulse Width)	200	mA		
Continuous Forward Current	150	mA		
Junction temperture	115	°C/W		
Reverse Voltage	5	V		
Operating Temperature Range	-40°C to +80°C			
Storage Temperature Range	-40°C to +80°C			
Lead Soldering Temperature [4mm(.157")From Body	260°C for 5 Seconds			

Electrical Optical Characteristics at Ta=25 ℃

Parameter	Symbo 1	Min.	Тур.	Max	Unit	Test Condition
luminous flux	φ	R25 G45 B10		R35 G55 B15	lm	I _f =150mA(Note 1)
Viewing Angle	$2\theta_{1/2}$		120		Deg	(Note 2)
Peak Emission Wavelength	λр	R620 G520 B465		R625 G525 B470	nm	I _f =150mA
Color Temperature	TC				K	I _f =150mA(Note 3)
Forward Voltage	V_{f}	R:2.0 G.B:3.0		R:2.4 G.B:3.2	V	I _f =150mA
Reverse Current	I_R			10	μА	$V_R=5V$

Notes:

- 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.
- 2. $\theta_{1/2}$ is the off-axis angle at which the luminous intensity is half the axial luminous intensity.
- 3. The dominant wavelength(λd) is derived from the CIE chromaticity diagram and represents the single wavelength which defines the color of the device.